

SN54LS682, SN54LS684, SN54LS685, SN54LS687, SN54LS688, SN74LS682, SN74LS684 THRU SN74LS688 8-BIT MAGNITUDE/IDENTITY COMPARATORS

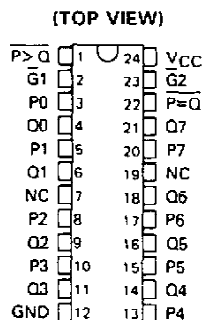
D2617, JANUARY 1981—REVISED MARCH 1988

SDLS008

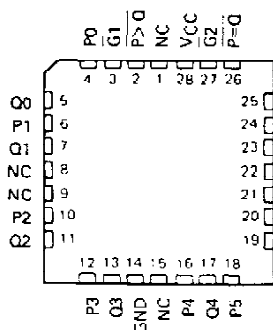
- Compares Two-8-Bit Words
- Choice of Totem-Pole or Open-Collector Outputs
- Hysteresis at P and Q Inputs
- 'LS682 has 20-k Ω Pullup Resistors on the Q Inputs
- SN74LS686 and 'LS687 . . . JT and NT 24-Pin, 300-Mil Packages

TYPE	P = Q	P > Q	OUTPUT ENABLE	OUTPUT CONFIGURATION	20-k Ω PULLUP
'LS682	yes	yes	no	totem-pole	yes
'LS684	yes	yes	no	totem-pole	no
'LS685	yes	yes	no	open-collector	no
SN74LS686	yes	yes	yes	totem-pole	no
'LS687	yes	yes	yes	open-collector	no
'LS688	yes	no	yes	totem-pole	no

SN54LS687 . . . JT PACKAGE
SN74LS686, SN74LS687 . . . DW OR NT PACKAGE



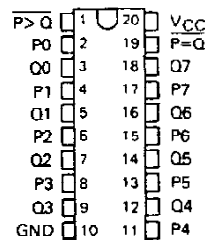
SN54LS687 . . . FK PACKAGE
(TOP VIEW)



NC—No internal connection

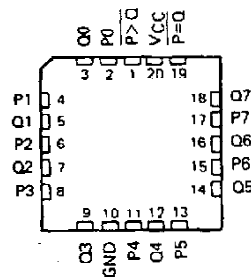
SN54LS682, SN54LS684, SN54LS685 . . . J PACKAGE
SN74LS682, SN74LS684, SN74LS685 . . . DW OR N PACKAGE

(TOP VIEW)



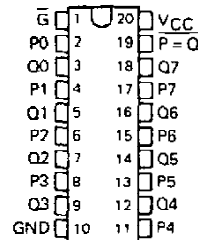
SN54LS682, SN54LS684, SN54LS685 . . . FK PACKAGE

(TOP VIEW)



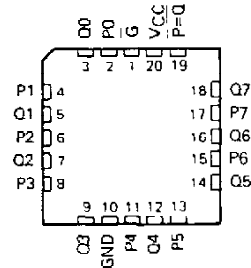
SN54LS688 . . . J PACKAGE
SN74LS688 . . . DW OR N PACKAGE

(TOP VIEW)



SN54LS688 . . . FK PACKAGE

(TOP VIEW)



PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

SN54LS682, SN54LS684, SN54LS685, SN54LS687, SN54LS688
SN74LS682, SN74LS684 THRU SN74LS688
8-BIT MAGNITUDE/IDENTITY COMPARATORS

description

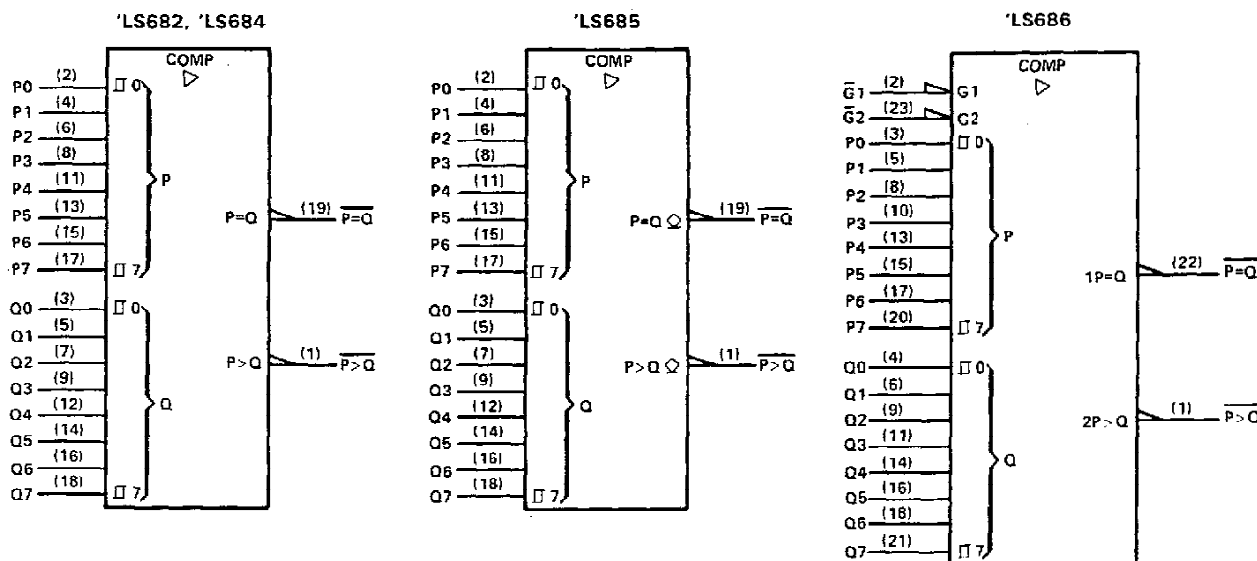
These magnitude comparators perform comparisons of two eight-bit binary or BCD words. All types provide $\overline{P=Q}$ outputs and all except 'LS688 provide $\overline{P>Q}$ outputs as well. The 'LS682, 'LS684, 'LS686, and 'LS688 have totem-pole outputs, while the 'LS685 and 'LS687 have open-collector outputs. The 'LS682 features 20-k Ω pullup termination resistors on the Q inputs for analog or switch data.

FUNCTION TABLE

INPUTS			OUTPUTS	
DATA	ENABLES		$\overline{P=Q}$	$\overline{P>Q}$
P, Q	$\overline{G}, \overline{G1}$	$\overline{G2}$		
$P=Q$	L	X	L	H
$P>Q$	X	L	H	L
$P<Q$	X	X	H	H
$P=Q$	H	X	H	H
$P>Q$	X	H	H	H
X	H	H	H	H

- NOTES: 1. The last three lines of the function table applies only to the devices having enable inputs, i.e., 'LS686 thru 'LS688.
2. The $\overline{P<Q}$ function can be generated by applying the $\overline{P=Q}$ and $\overline{P>Q}$ outputs to a 2-input NAND gate.
3. For 'LS686 and 'LS687, $\overline{G1}$ enables $\overline{P=Q}$ and $\overline{G2}$ enables $\overline{P>Q}$.

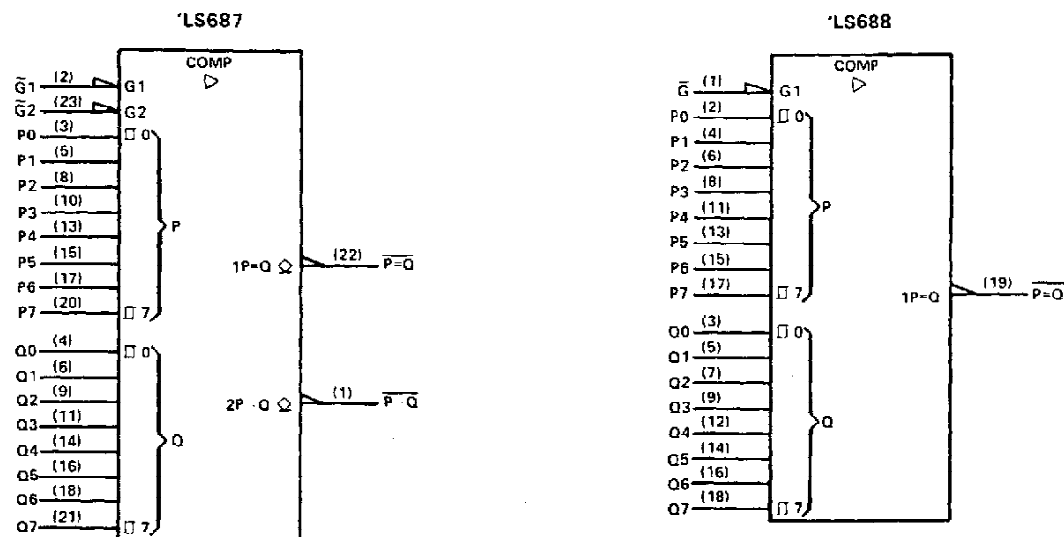
logic symbols†



†These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, J, JT, N, and NT packages.

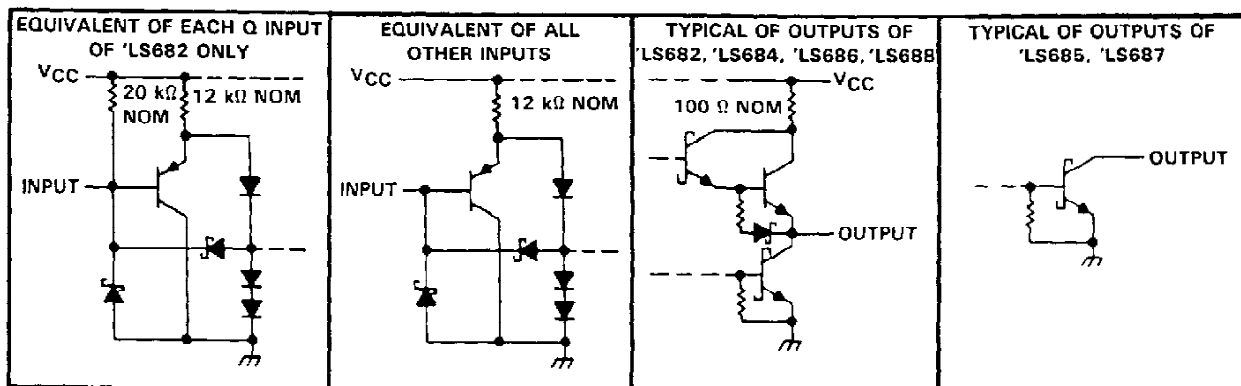
**SN54LS682, SN54LS684, SN54LS685, SN54LS687, SN54LS688,
SN74LS682, SN74LS684 THRU SN74LS688
8-BIT MAGNITUDE/IDENTITY COMPARATORS**

logic symbols† (continued)



†These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for DW, J, JT, N, and NT packages.

schematics of inputs and outputs

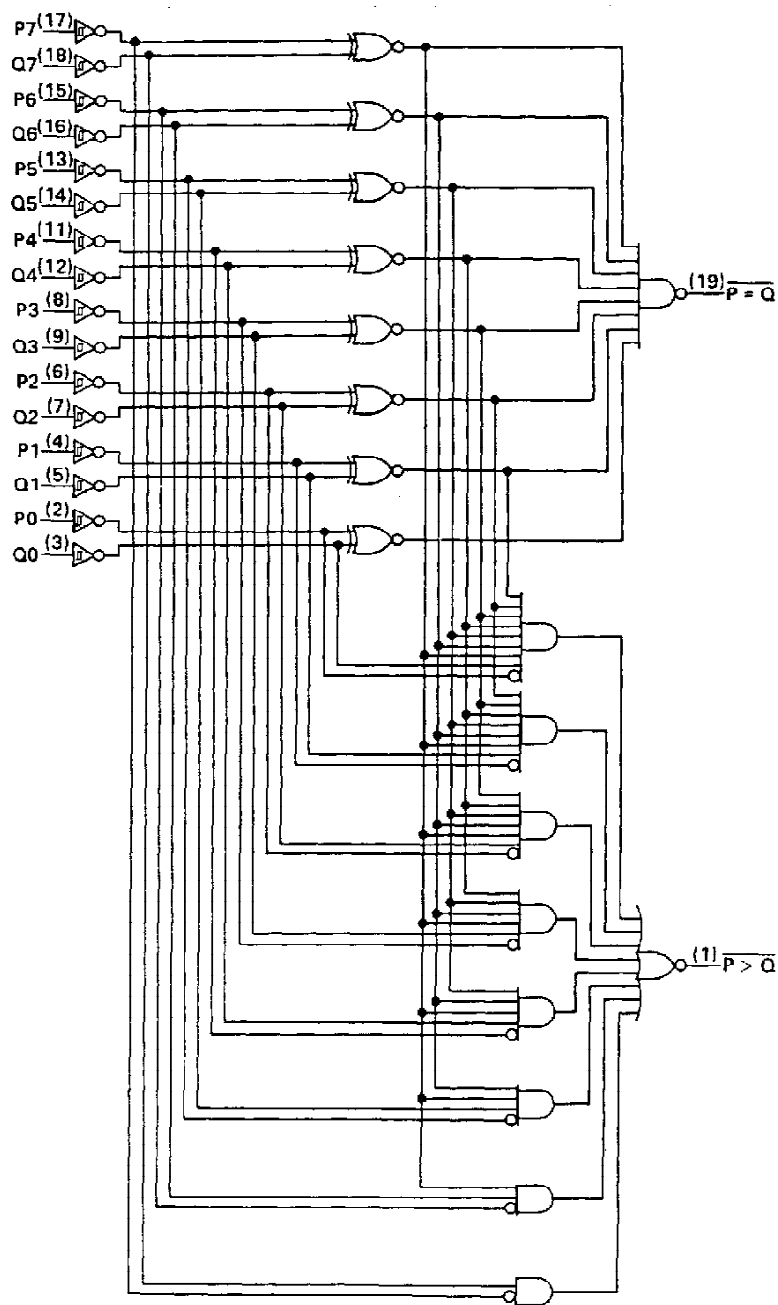


**TEXAS
INSTRUMENTS**

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

**SN54LS682, SN54LS684, SN54LS685
SN74LS682, SN74LS684, SN74LS685
8-BIT MAGNITUDE/IDENTITY COMPARATORS**

'LS682, 'LS684, 'LS685 logic diagram (positive logic)



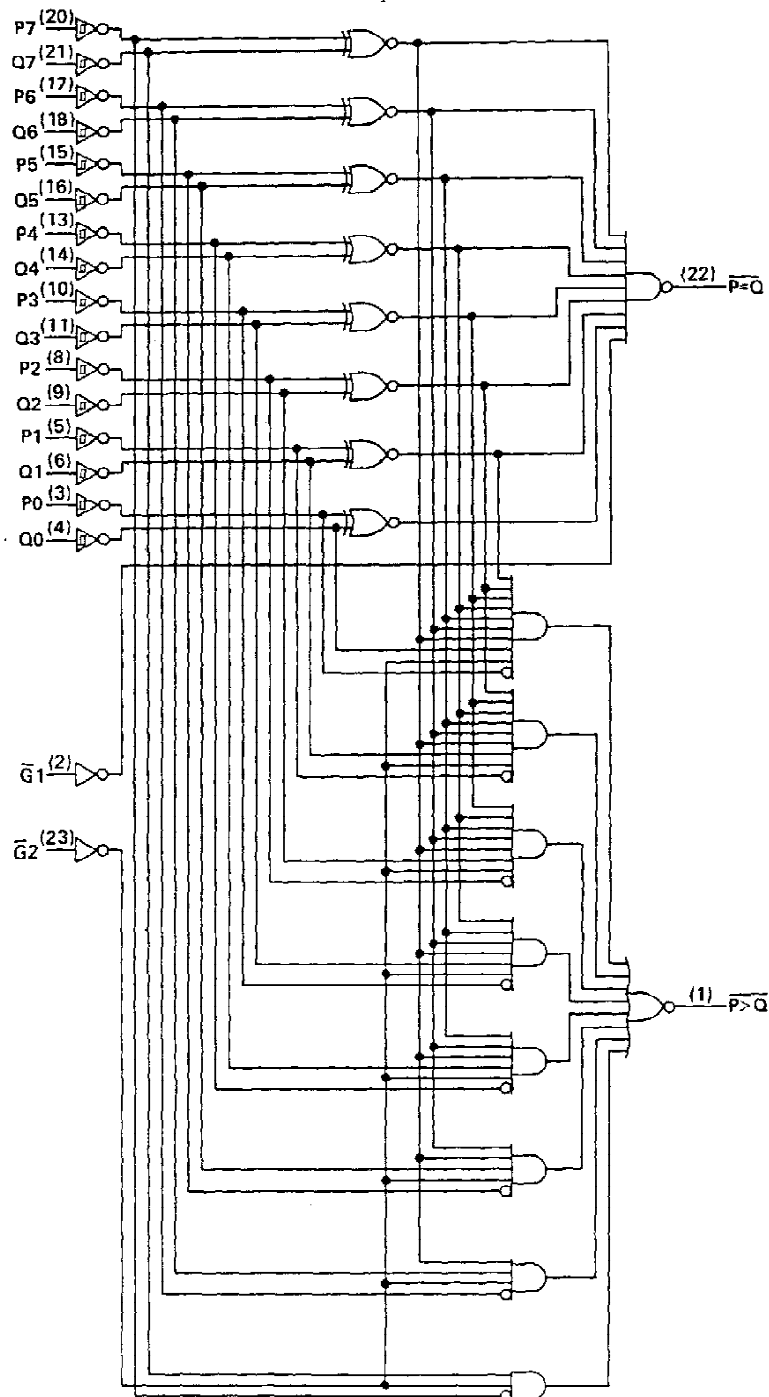
Pin numbers shown are for DW, J, and N packages.

**TEXAS
INSTRUMENTS**

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

SN54LS687
SN74LS686, SN74LS687
8-BIT MAGNITUDE/IDENTITY COMPARATORS

'LS686, 'LS687 logic diagram (positive logic)



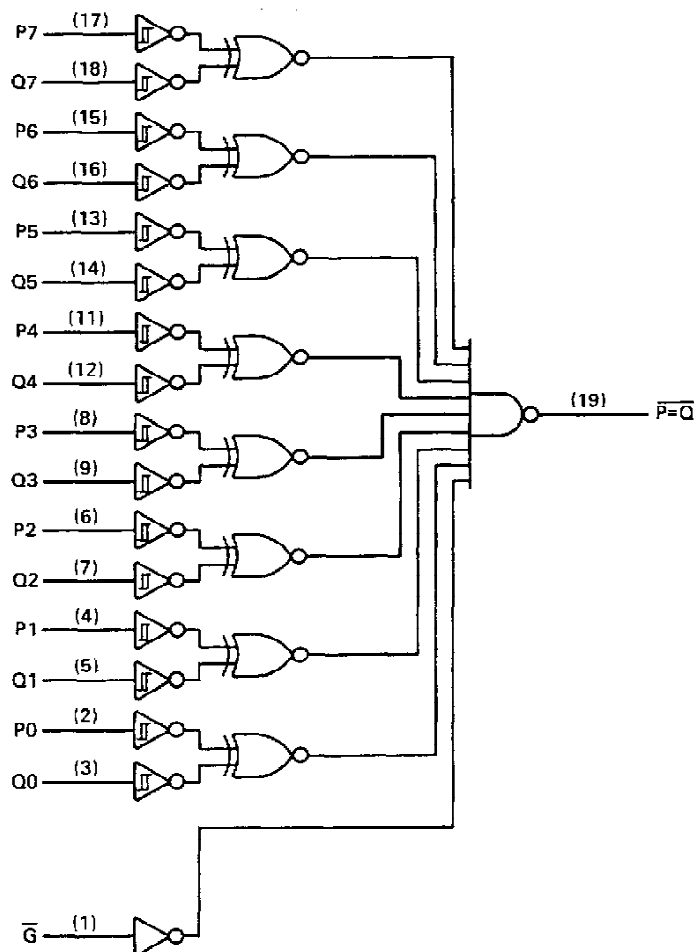
Pin numbers shown are for DW, JT, and NT packages.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

**SN54LS682, SN54LS684, SN54LS685, SN54LS687, SN54LS688
SN74LS682, SN74LS684 THRU SN74LS688
8-BIT IDENTITY COMPARATORS**

'LS688 logic diagram (positive logic)



Pin numbers shown are for DW, J, and N packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage: Q inputs of 'LS682	5.5 V
All other inputs	7 V
Off-state output voltage: 'LS685, 'LS687	7 V
Operating free-air temperature range:	
SN54LS682, SN54LS684, SN54LS685, SN54LS687, SN54LS688	-55°C to 125°C
SN74LS682, SN74LS684 thru SN74LS688	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

SN54LS682, SN54LS684, SN54LS688
SN74LS682, SN74LS684, SN74LS686, SN74LS688
8-BIT MAGNITUDE/IDENTITY COMPARATORS WITH TOTEM-POLE OUTPUTS

recommended operating conditions

	SN54LS [*]			SN74LS [*]			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.85	5	5.25	V
High-level output current, I_{OH}			-400			-400	μ A
Low-level output current, I_{OL}			12			24	mA
Operating free-air temperature, T_A	-55		125	0		70	$^{\circ}$ C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†	SN54LS*		SN74LS*		UNIT
				MIN	TYP‡	MAX	MIN	
V_{IH}	High-level input voltage			2		2		V
V_{IL}	Low-level input voltage			0.7		0.8		V
$V_{T+} - V_{T-}$	Hysteresis	P or Q inputs	$V_{CC} = \text{MIN}$	0.4		0.4		V
V_{IK}	Input clamp voltage		$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$	-1.5		-1.5		V
V_{OH}	High-level output voltage		$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = V_{IL\text{max}}, I_{OH} = -400 \mu\text{A}$	2.5		2.7		V
V_{OL}	Low-level output voltage		$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = V_{IL\text{max}}, I_{OL} = 12 \text{ mA}$	0.25	0.4	0.25	0.4	V
			$I_{OL} = 24 \text{ mA}$			0.35	0.5	
I_I	Input current at maximum input voltage	Q inputs, 'LS682	$V_{CC} = \text{MAX}, V_I = 5.5 \text{ V}$	0.1		0.1		mA
	All other inputs	$V_{CC} = \text{MAX}, V_I = 7 \text{ V}$						
I_{IH}	High-level input current		$V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$	20		20		μA
I_{IL}	Low-level input current	Q inputs, 'LS682	$V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$	-0.4		-0.4		mA
		All other inputs		-0.2		-0.2		
$I_{OS}^{\S}$	Short-circuit output current		$V_{CC} = \text{MAX}, V_O = 0$	-20	-100	-20	-100	mA
I_{CC}	Supply current	'LS682	$V_{CC} = \text{MAX},$ See Note 1	42	70	42	70	mA
		'LS684		40	65	40	65	
		'LS686		44	75	44	75	
		'LS688		40	65	40	65	

[†] For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$.

^{\S} Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 1: I_{CC} is measured with any $\bar{Q}$ inputs grounded, all other inputs at 4.5 V, and all outputs open.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

SN54LS682, SN54LS684, SN54LS688
SN74LS682, SN74LS684, SN74LS686, SN74LS688
8-BIT MAGNITUDE/IDENTITY COMPARATORS WITH TOTEM-POLE OUTPUTS

switching characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER†	FROM (INPUTS)	TO (OUTPUT)	TEST CONDITIONS	'LS682		'LS684		'LS686		'LS688		UNIT
				MIN	TYP MAX	MIN	TYP MAX	MIN	TYP MAX	MIN	TYP MAX	
tPLH	P	$\overline{P} = \overline{Q}$	RL = 667 Ω, CL = 45 pF, All other inputs low, See Note 2	13	25	15	25	13	25	12	18	ns
tPHL				15	25	17	25	20	30	17	23	
tPLH	Q	$\overline{P} = \overline{Q}$		14	26	16	25	13	25	12	18	ns
tPHL				15	25	15	25	21	30	17	23	
tPLH	$\overline{Q}, \overline{Q}1$	$\overline{P} = \overline{Q}$						11	20	12	18	ns
tPHL								19	30	13	20	
tPLH	P	$\overline{P} > \overline{Q}$		20	30	22	30	19	30			ns
tPHL				15	30	17	30	15	30			
tPLH	Q	$\overline{P} > \overline{Q}$		21	30	24	30	18	30			ns
tPHL				19	30	20	30	19	30			
tPLH	$\overline{Q}2$	$\overline{P} > \overline{Q}$						21	30			ns
tPHL								16	25			

† t_{PLH} = propagation delay time, low-to-high-level outputs; t_{PHL} = propagation delay time, high-to-low-level output.

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

SN54LS685, SN54LS687
SN74LS685, SN74LS687, SN74LS688

8-BIT MAGNITUDE/IDENTITY COMPARATORS WITH TOTEM-POLE OUTPUTS

recommended operating conditions

	SN54LS [*]			SN74LS [*]			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.85	5	5.25	V
High-level output current, I_{OH}			5.5			5.5	V
Low-level output current, I_{OL}			12			24	mA
Operating free-air temperature, T_A	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS [†]	SN54LS [*]			SN74LS [*]			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.7			0.8	V
$V_{T+} - V_{T-}$	Hysteresis	P or Q inputs		0.4			0.4		V
V_{IK}	Input clamp voltage	$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$			-1.5			-1.5	V
I_{OH}	High-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = V_{ILmax}, V_{OH} = 5.5 \text{ V}$			250			100	μA
V_{OL}	Low-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = V_{ILmax}, I_{OL} = 12 \text{ mA}$	0.25	0.4		0.25	0.4		V
		$I_{OL} = 24 \text{ mA}$				0.35	0.5		
I_I		$V_{CC} = \text{MAX}, V_I = 7 \text{ V}$		0.1			0.1		mA
I_{IH}	High-level input current	$V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$		20			20		μA
I_{IL}	Low-level input current	$V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$		-0.2			-0.2		mA
I_{CC}	Supply current	'LS685		40	65		40	65	mA
		'LS687		44	75		44	75	

[†]For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

^{*}All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

NOTE 1: I_{CC} is measure with any $\bar{Q}$ inputs grounded, all other inputs at 4.5 V, and all outputs open.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

SN54LS685, SN54LS687

SN74LS685, SN74LS687

8-BIT MAGNITUDE/IDENTITY COMPARATORS WITH OPEN-COLLECTOR OUTPUTS

switching characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS685			'LS687			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
t _{PLH}	P	$\overline{P=Q}$	R _L = 667 Ω, C _L = 45 pF, All other inputs low, See Note 2		30	45		24	35	ns
t _{PHL}					19	35		20	30	
t _{PLH}	Q	$\overline{P=Q}$			24	45		24	35	ns
t _{PHL}					23	35		20	30	
t _{PLH}	$\overline{Q}, \overline{Q1}$	$\overline{P=Q}$						21	35	ns
t _{PHL}								18	30	
t _{PLH}	P	$\overline{P>Q}$			32	45		24	35	ns
t _{PHL}					16	35		16	30	
t _{PLH}	Q	$\overline{P>Q}$			30	45		24	35	ns
t _{PHL}					20	35		16	30	
t _{PLH}	$\overline{Q2}$	$\overline{P>Q}$						24	35	ns
t _{PHL}								15	30	

[†] t_{PLH} = propagation delay time, low-to-high-level outputs; t_{PHL} = propagation delay time, high-to-low-level output.

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75286

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
84151012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
84151012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8415101RA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
8415101RA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
8415101SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
8415101SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
84152012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8415201RA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
8415201SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
84153012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8415301RA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
8415301SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
SN54LS682J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS682J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS684J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS688J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN74LS682DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS682N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS682NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS682NE4	ACTIVE	PDIP	N	20	20	Pb-Free	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
(RoHS)								
SN74LS682NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS684NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS684NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS686DW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI
SN74LS686NT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SN74LS687NT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SN74LS687NT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SN74LS688DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LS688N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS688N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74LS688NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS688NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS682FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS682FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS682J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS682J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS682W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
SNJ54LS682W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
SNJ54LS684FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS684J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS684W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
SNJ54LS688FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS688J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS688W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

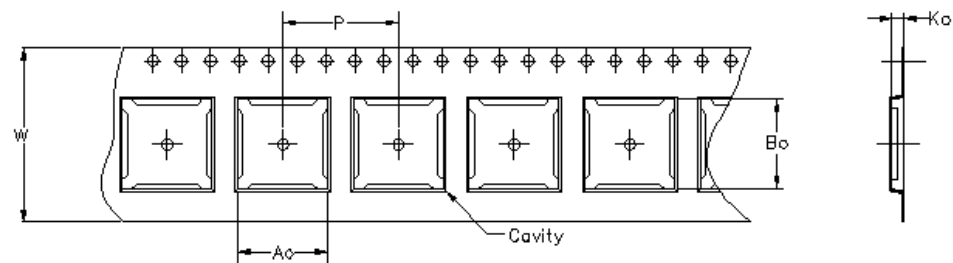
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

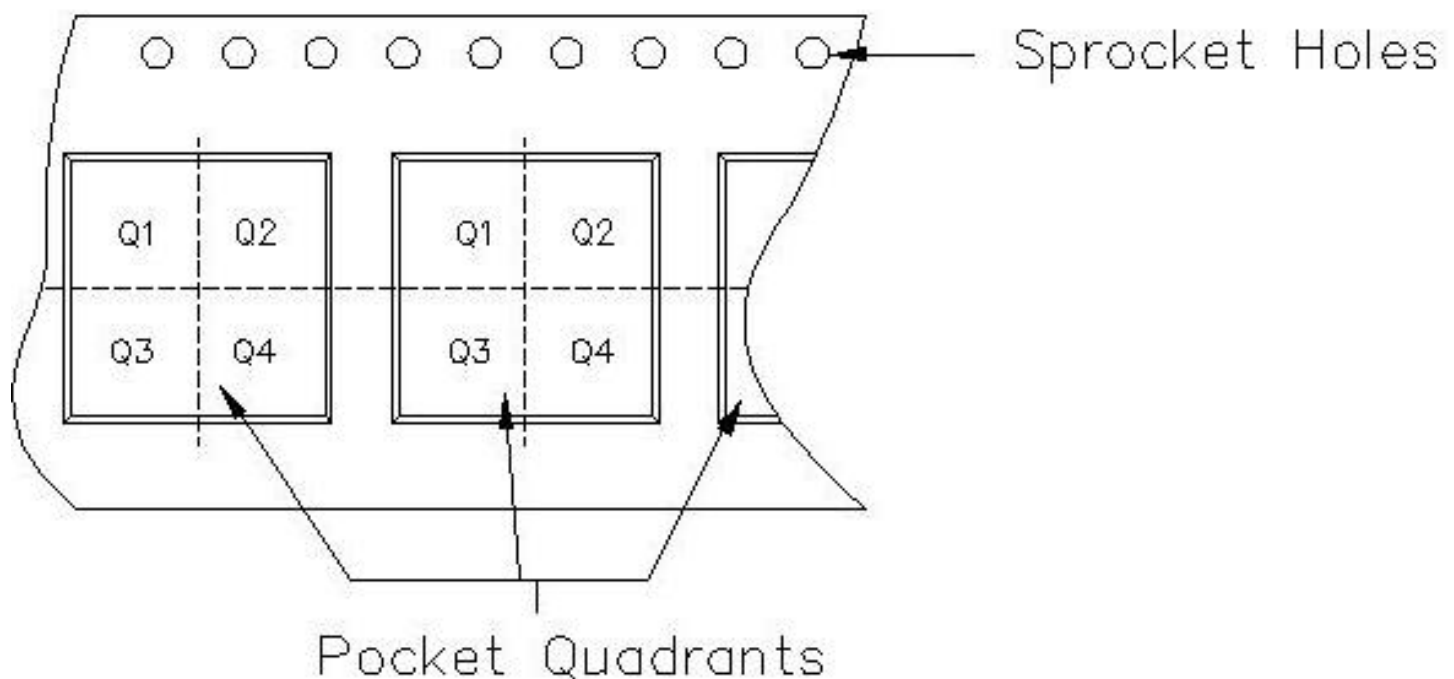
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



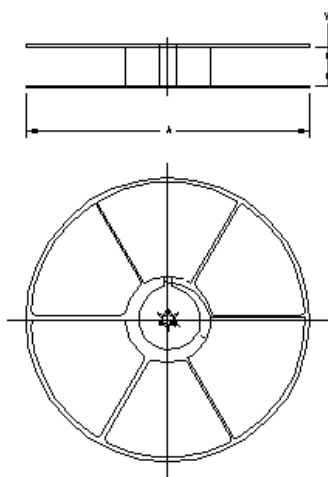
Carrier tape design is defined largely by the component length, width, and thickness.

A_0 = Dimension designed to accommodate the component width.
B_0 = Dimension designed to accommodate the component length.
K_0 = Dimension designed to accommodate the component thickness.
W = Overall width of the carrier tape.
P = Pitch between successive cavity centers.



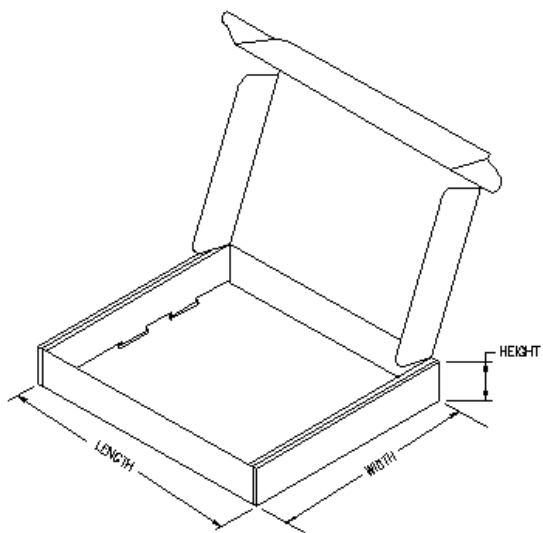
TAPE AND REEL INFORMATION

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS682DWR	DW	20	MLA	330	24	10.8	13.0	2.7	12	24	Q1
SN74LS682NSR	NS	20	MLA	330	24	8.2	13.0	2.5	12	24	Q1
SN74LS684DWR	DW	20	MLA	330	24	10.8	13.0	2.7	12	24	Q1
SN74LS684NSR	NS	20	MLA	330	24	8.2	13.0	2.5	12	24	Q1
SN74LS688DWR	DW	20	MLA	330	24	10.8	13.0	2.7	12	24	Q1
SN74LS688NSR	NS	20	MLA	330	24	8.2	13.0	2.5	12	24	Q1



TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74LS682DWR	DW	20	MLA	333.2	333.2	31.75
SN74LS682NSR	NS	20	MLA	333.2	333.2	31.75
SN74LS684DWR	DW	20	MLA	333.2	333.2	31.75
SN74LS684NSR	NS	20	MLA	333.2	333.2	31.75
SN74LS688DWR	DW	20	MLA	333.2	333.2	31.75
SN74LS688NSR	NS	20	MLA	333.2	333.2	31.75



J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
84151012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8415101RA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
8415101RA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
8415101SA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
8415101SA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
84152012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8415201RA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
8415201SA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
84153012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8415301RA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
8415301SA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
SN54LS682J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS682J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS684J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS688J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN74LS682DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS682N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS682NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS682NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LS682NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS684NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS684NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS686DW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI
SN74LS686NT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SN74LS687NT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SN74LS687NT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SN74LS688DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688N	ACTIVE	PDIP	N	20	20	Pb-Free	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
(RoHS)								
SN74LS688N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74LS688NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS688NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS682FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS682FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS682J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS682J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS682W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
SNJ54LS682W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
SNJ54LS684FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS684J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS684W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
SNJ54LS688FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS688J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS688W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

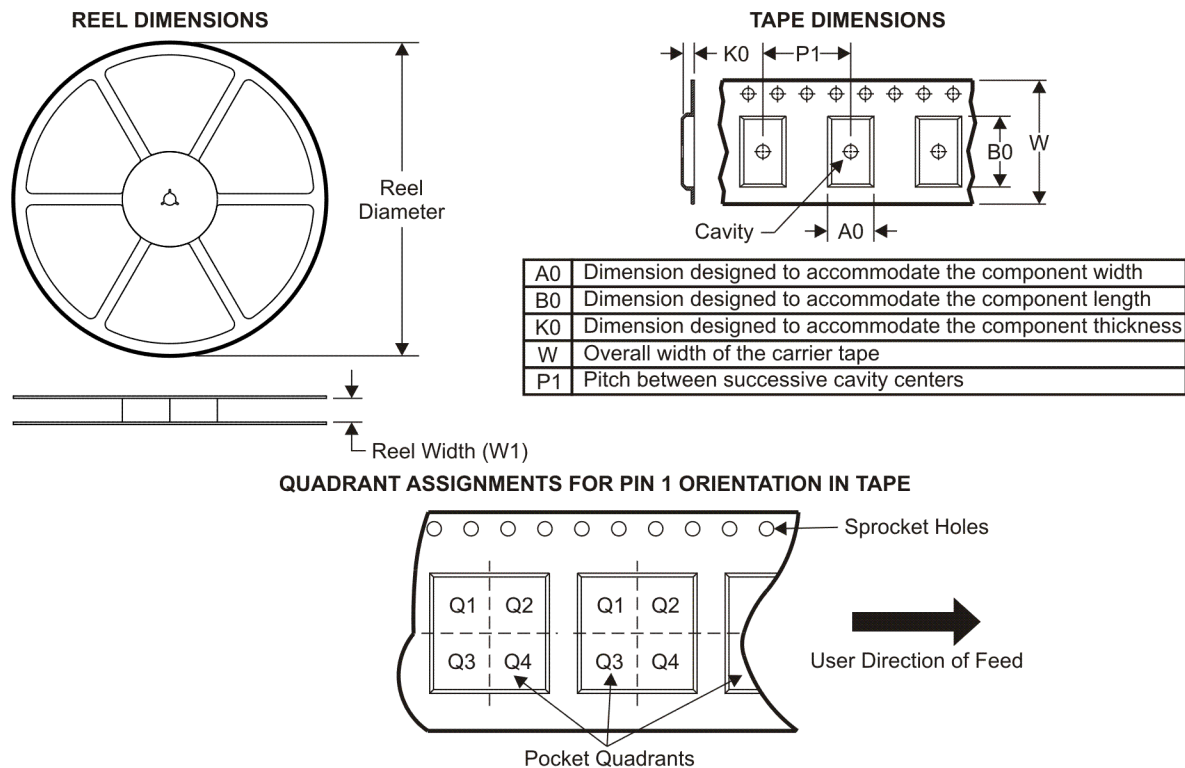
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

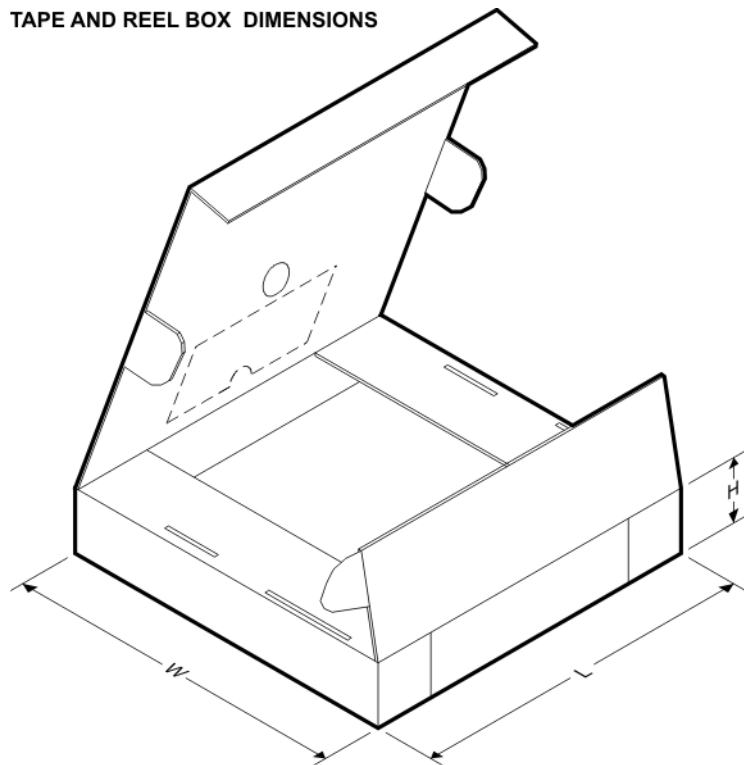
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS682DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74LS682NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74LS684DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74LS684NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74LS688DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74LS688NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS682DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74LS682NSR	SO	NS	20	2000	346.0	346.0	41.0
SN74LS684DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74LS684NSR	SO	NS	20	2000	346.0	346.0	41.0
SN74LS688DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74LS688NSR	SO	NS	20	2000	346.0	346.0	41.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



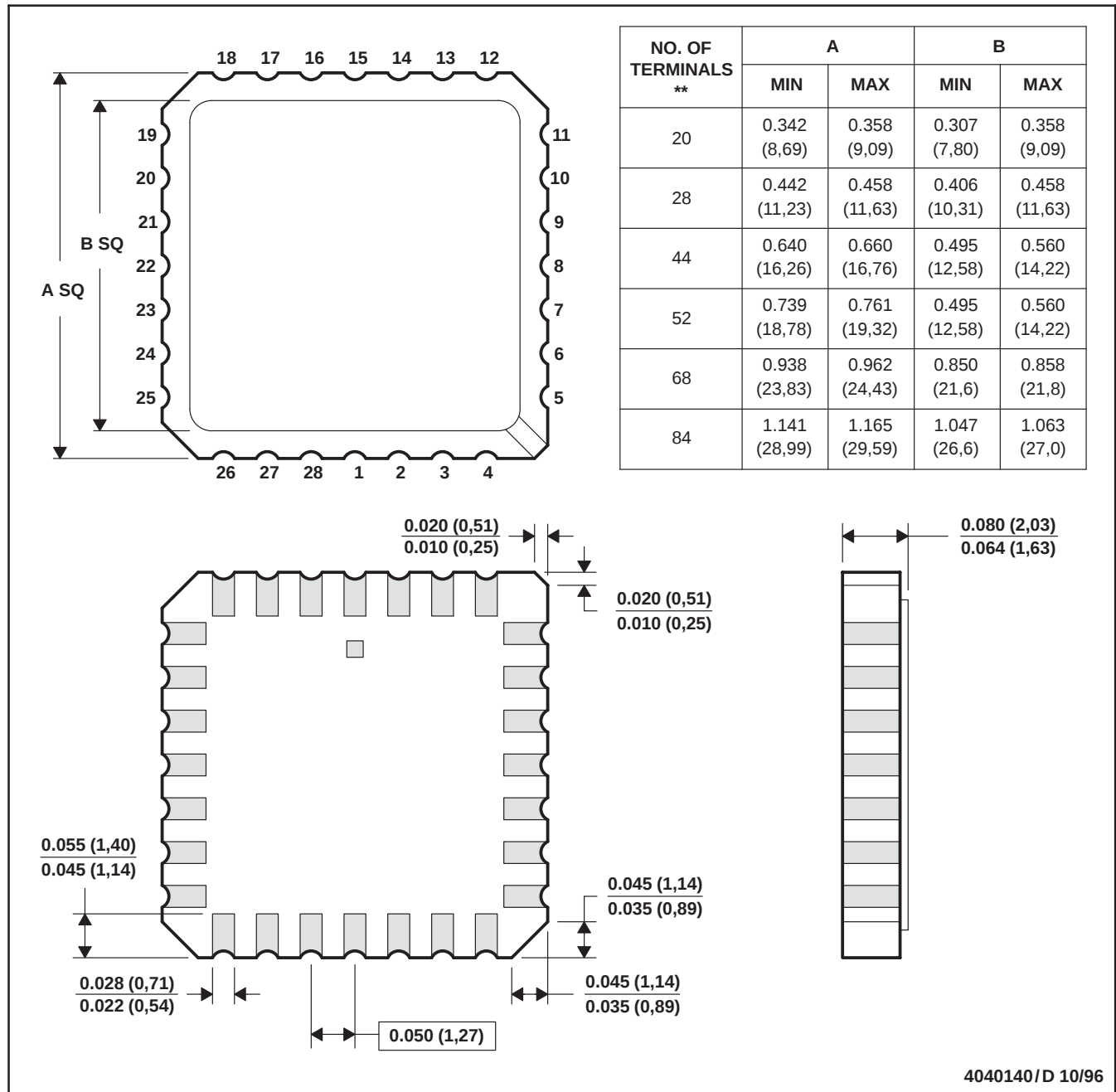
4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MS-004

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



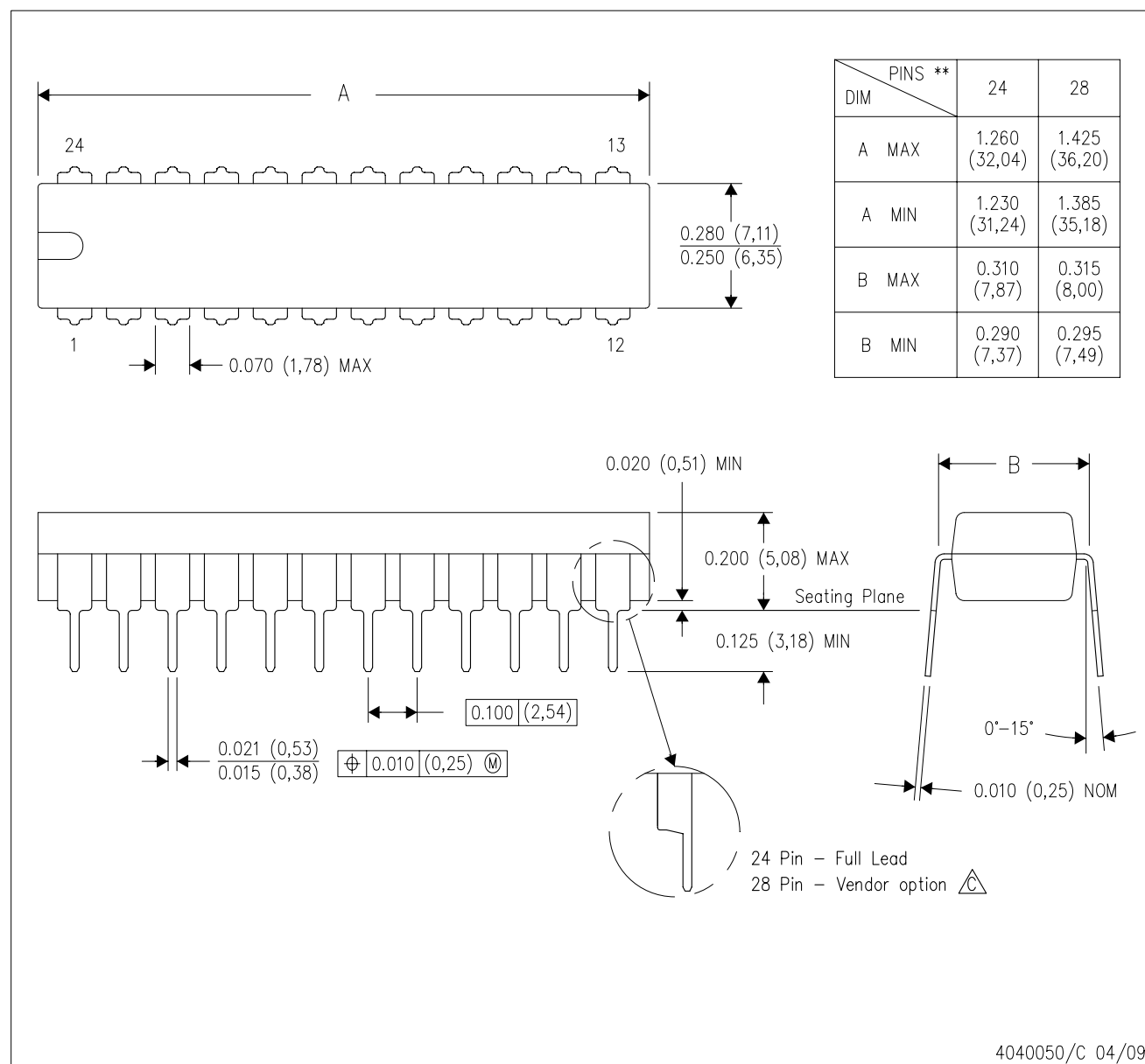
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

MECHANICAL DATA

NT (R-PDIP-T**)

24 PINS SHOWN

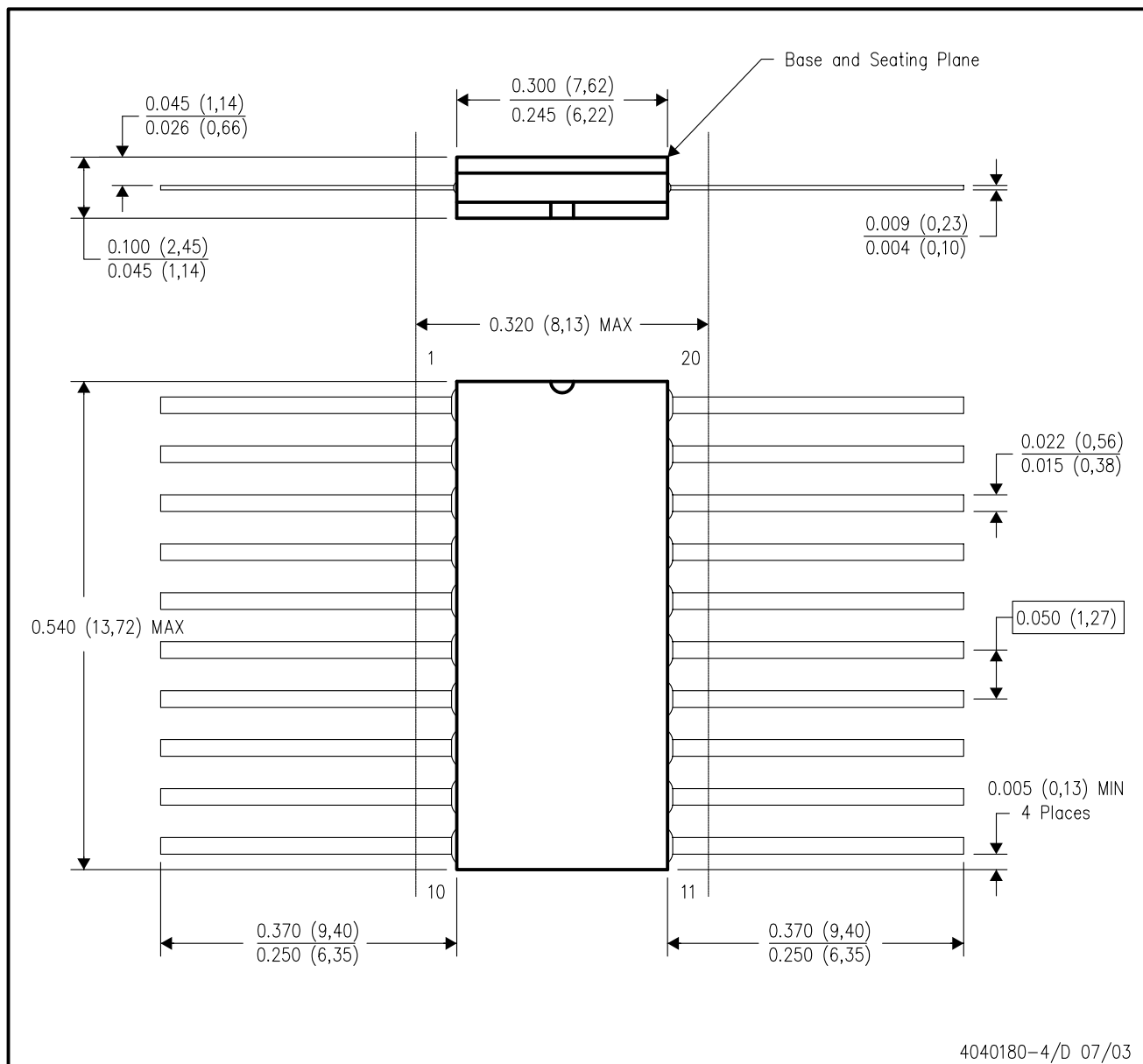
PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
B. This drawing is subject to change without notice.
C. The 28 pin end lead shoulder width is a vendor option, either half or full width.

W (R-GDFP-F20)

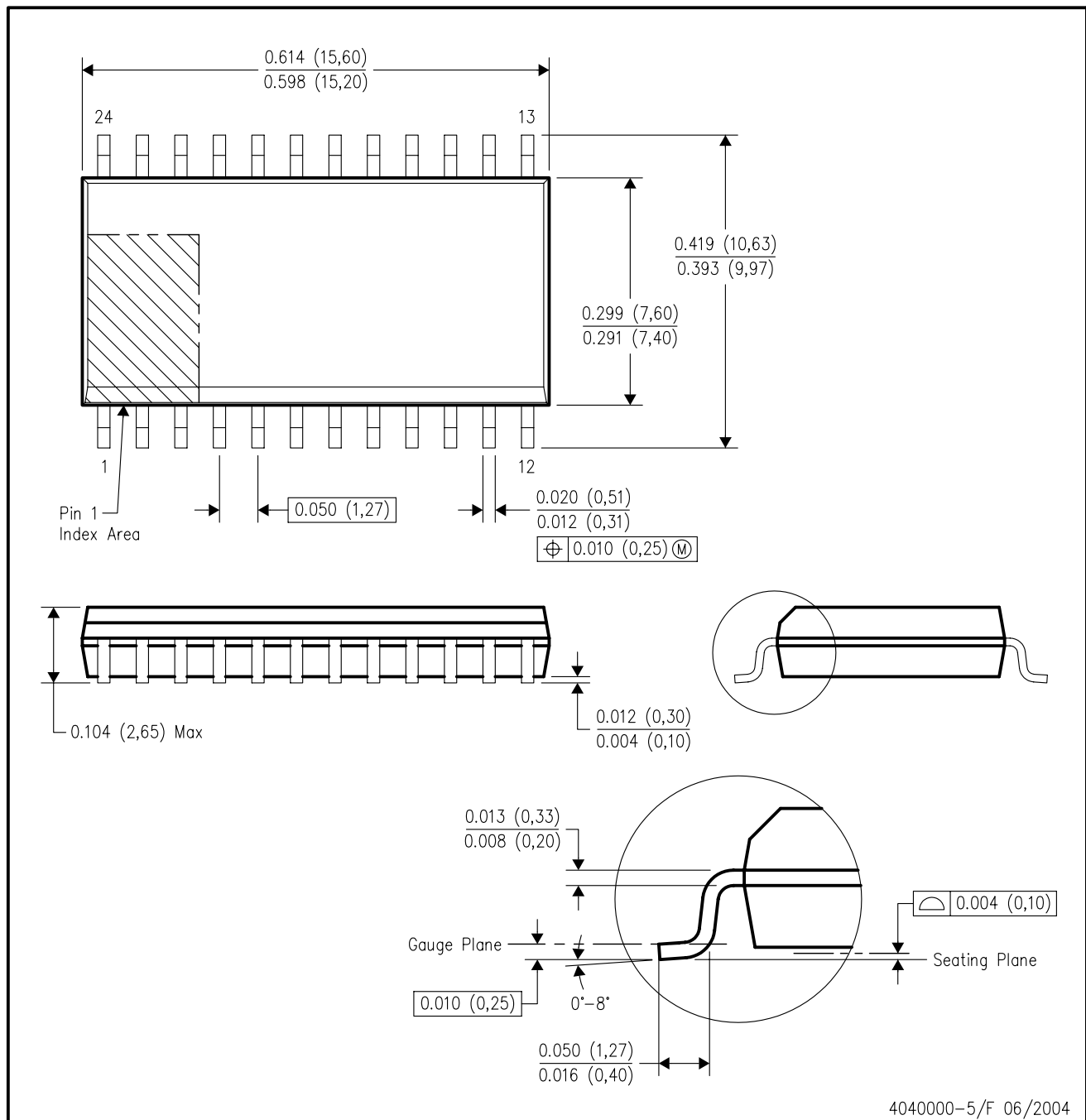
CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within Mil-Std 1835 GDFP2-F20

DW (R-PDSO-G24)

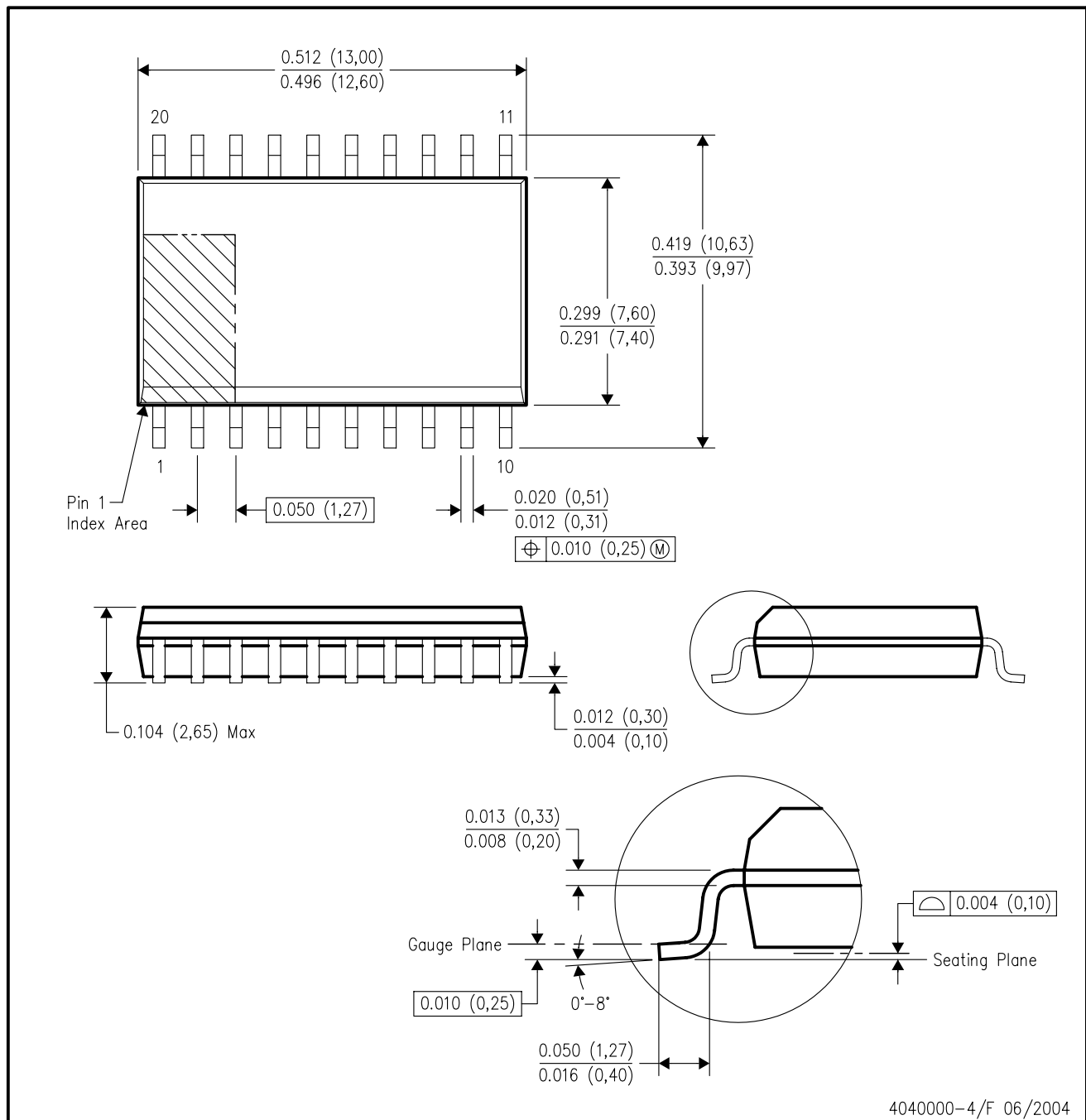
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-013 variation AD.

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2009, Texas Instruments Incorporated